IN THE CLAIMS:

Please amend the claims as follows:

1. (Original) Apparatus for electro-chemical deposition on a substrate, comprising:

an annular conductive body adapted to support the substrate and having at least one pin receiving pocket formed therein; and

at least one electrical contact pin having a portion brazed in the receiving pocket, the contact pin adapted to electrically bias the substrate.

2. (Original) The apparatus of claim 1, wherein the contact pin is an annular ring.

3. (Original) The apparatus of claim 1, wherein the contact pin is a plurality of arc segments.

4. (Original) The apparatus of claim 1, wherein the contact pin is a plurality of cylindrical posts.

5. (Original) The apparatus of claim 1, wherein the conductive body further comprises:

a first surface;

a shoulder coupled to the first surface; and

a substrate support surface extending inward from the shoulder and supporting the electrical contact pin thereon, the substrate support surface and shoulder defining a substrate receiving pocket.

6. (Currently Amended) The apparatus of claim 1, wherein the contact pin is comprised of platinum or platinum alloy.

7. (Original) The apparatus of claim 1 further comprising:

a dielectric covering at least partially encapsulating the conductive body.

8. (Original) The apparatus of claim 7, wherein the contact pin further comprises:

a portion extending from the conductive body and having a contact surface free from the dielectric covering.

9. (Currently Amended) Apparatus for electro-chemical deposition on a substrate, comprising:

an annular conductive body adapted to support the substrate and having at least one pin receiving slot ~~pocket~~ formed therein;

at least one electrical contact pin having a portion brazed in the receiving slot, the contact pin adapted to electrically bias the substrate proximate the substrate's perimeter; and

a first seal disposed inward of the electrical contact pin and providing a seal with the conductive body.

10. (Original) The apparatus of claim 9, wherein the contact pin is an annular ring.

11. (Original) The apparatus of claim 9, wherein the contact pin is a plurality of arc segments.

12. (Original) The apparatus of claim 9, wherein the contact pin is a plurality of cylindrical posts.

13. (Original) The apparatus of claim 9, wherein the conductive body further comprises:

a first surface;

a shoulder coupled to the first surface;

a substrate support surface extending inward from the shoulder and supporting the electrical contact pin thereon, the substrate support surface and shoulder defining a substrate receiving pocket; and

an inner ring surface disposed radially inward of the substrate support surface, the inner ring surface in sealing communication with the first seal.

14. (Currently Amended) The apparatus of claim 9, wherein the contact pin is comprised of platinum or platinum alloy.

15. (Original) The apparatus of claim 9 further comprising:

a dielectric covering at least partially encapsulating the conductive body.

16. (Original) The apparatus of claim 15, wherein the contact pin further comprises:

a portion extending from the conductive body and having a contact surface free from the dielectric covering.

17. (Previously Presented) Apparatus for electro-chemical deposition on a substrate, comprising:

an annular conductive body adapted to support the substrate and having at least one pin receiving pocket formed therein;

a dielectric covering at least partially encapsulating the conductive body; and

at least one electrical contact pin having a portion brazed in the receiving pocket, the contact pin adapted to electrically bias the substrate proximate the substrate's perimeter and having an exposed portion extending from the conductive body and having a contact surface free from the dielectric covering.

Claims 18-36 (Canceled)

37. (New) The apparatus of claim 1, wherein the contact pin includes a plurality of posts.

38. (New) The apparatus of claim 9, wherein the contact pin includes a plurality of posts.

39. (New) An apparatus for electro-chemical deposition on a substrate, comprising:

an annular conductive body made of a first metal and having a substrate seating surface formed on a top surface thereof and adapted to support the substrate, the substrate seating surface disposed between a downward angled

shoulder of the conductive body and an inner diameter of the conductive body and having at least one pin receiving recess formed therein;

at least one electrical contact pin made of a second metal different from the first metal and selected from the group consisting of platinum and platinum alloys, the at least one electrical contact pin having a base portion brazed in the receiving recess and an upper exposed portion extending from the conductive body and adapted to electrically bias the substrate proximate the perimeter of the substrate;

a dielectric covering at least partially encapsulating the conductive body;

an electrical lead coupled to a power source and the conductive body through the dielectric covering in order to supply power to the at least one electrical contact pin; and

a seal coupled to the contact ring proximate the inner diameter and disposed inward of the electrical contact pin, the seal adapted to provide sealing contact with the substrate.

40. (New) An apparatus for electro-chemical deposition on a substrate, comprising:

an annular conductive body made of a first metal and having a substrate seating surface formed on a top surface thereof and adapted to support the substrate, the substrate seating surface disposed between a downward angled shoulder of the conductive body and an inner diameter of the conductive body and having at least one pin receiving recess formed therein;

at least one electrical contact pin made of a second metal different from the first metal and selected from the group consisting of platinum and platinum alloys, the at least one electrical contact pin having a base portion brazed in the receiving recess and an upper exposed portion extending from the conductive body and adapted to electrically bias the substrate proximate the perimeter of the substrate; and

a dielectric covering encapsulating the conductive body.